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Details

Product Status	Active
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	24MHz
Connectivity	I ² C, IrDA, LINbus, Microwire, SmartCard, SPI, SSP, UART/USART
Peripherals	Brown-out Detect/Reset, CapSense, LCD, POR, PWM, WDT
Number of I/O	36
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.71V ~ 5.5V
Data Converters	A/D 16x10b Slope, 16x12b SAR; D/A 2xIDAC
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-TQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy8c4126azi-s433

Pinouts

The following table provides the pin list for PSoC 4100S for the 48-pin TQFP, 44-pin TQFP, 40-pin QFN, 32-pin QFN, and 35-ball CSP packages. All port pins support GPIO.

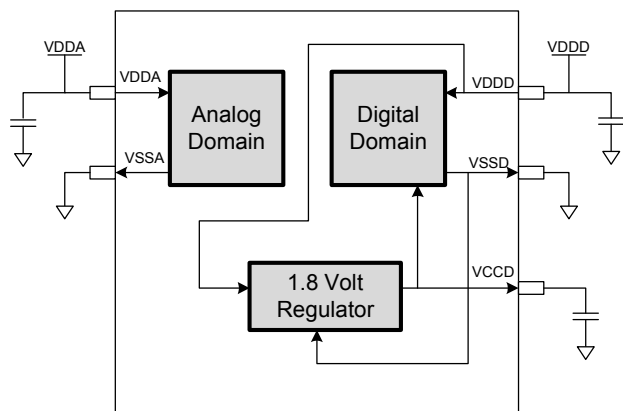
Table 1. Pin List

48-TQFP		44-TQFP		40-QFN		32-QFN		35-CSP	
Pin	Name	Pin	Name	Pin	Name	Pin	Name	Pin	Name
28	P0.0	24	P0.0	22	P0.0	17	P0.0	C3	P0.0
29	P0.1	25	P0.1	23	P0.1	18	P0.1	A5	P0.1
30	P0.2	26	P0.2	24	P0.2	19	P0.2	A4	P0.2
31	P0.3	27	P0.3	25	P0.3	20	P0.3	A3	P0.3
32	P0.4	28	P0.4	26	P0.4	21	P0.4	B3	P0.4
33	P0.5	29	P0.5	27	P0.5	22	P0.5	A6	P0.5
34	P0.6	30	P0.6	28	P0.6	23	P0.6	B4	P0.6
35	P0.7	31	P0.7	29	P0.7			B5	P0.7
36	XRES	32	XRES	30	XRES	24	XRES	B6	XRES
37	VCCD	33	VCCD	31	VCCD	25	VCCD	A7	VCCD
38	VSSD			DN	VSSD	26	VSSD	B7	VSS
39	VDDD	34	VDDD	32	VDDD			C7	VDD
40	VDDA	35	VDDA	33	VDDA	27	VDD	C7	VDD
41	VSSA	36	VSSA	34	VSSA	28	VSSA	B7	VSS
42	P1.0	37	P1.0	35	P1.0	29	P1.0	C4	P1.0
43	P1.1	38	P1.1	36	P1.1	30	P1.1	C5	P1.1
44	P1.2	39	P1.2	37	P1.2	31	P1.2	C6	P1.2
45	P1.3	40	P1.3	38	P1.3	32	P1.3	D7	P1.3
46	P1.4	41	P1.4	39	P1.4			D4	P1.4
47	P1.5	42	P1.5					D5	P1.5
48	P1.6	43	P1.6					D6	P1.6
1	P1.7/VREF	44	P1.7/VREF	40	P1.7/VREF	1	P1.7/VREF	E7	P1.7/VREF
		1	VSSD						
2	P2.0	2	P2.0	1	P2.0	2	P2.0		
3	P2.1	3	P2.1	2	P2.1	3	P2.1		
4	P2.2	4	P2.2	3	P2.2	4	P2.2	D3	P2.2
5	P2.3	5	P2.3	4	P2.3	5	P2.3	E4	P2.3
6	P2.4	6	P2.4	5	P2.4			E5	P2.4
7	P2.5	7	P2.5	6	P2.5	6	P2.5	E6	P2.5
8	P2.6	8	P2.6	7	P2.6	7	P2.6	E3	P2.6
9	P2.7	9	P2.7	8	P2.7	8	P2.7	E2	P2.7
10	VSSD	10	VSSD	9	VSSD				
12	P3.0	11	P3.0	10	P3.0	9	P3.0	E1	P3.0
13	P3.1	12	P3.1	11	P3.1	10	P3.1	D2	P3.1
14	P3.2	13	P3.2	12	P3.2	11	P3.2	D1	P3.2
16	P3.3	14	P3.3	13	P3.3	12	P3.3	C1	P3.3
17	P3.4	15	P3.4	14	P3.4			C2	P3.4
18	P3.5	16	P3.5	15	P3.5				

Power

The following power system diagram shows the set of power supply pins as implemented for the PSoC 4100S. The system has one regulator in Active mode for the digital circuitry. There is no analog regulator; the analog circuits run directly from the V_{DD} input.

Figure 4. Power Supply Connections



There are two distinct modes of operation. In Mode 1, the supply voltage range is 1.8 V to 5.5 V (unregulated externally; internal regulator operational). In Mode 2, the supply range is 1.8 V \pm 5% (externally regulated; 1.71 to 1.89, internal regulator bypassed).

Mode 1: 1.8 V to 5.5 V External Supply

In this mode, the PSoC 4100S is powered by an external power supply that can be anywhere in the range of 1.8 to 5.5 V. This range is also designed for battery-powered operation. For example, the chip can be powered from a battery system that starts at 3.5 V and works down to 1.8 V. In this mode, the internal regulator of the PSoC 4100S supplies the internal logic and its output is connected to the V_{CCD} pin. The V_{CCD} pin must be bypassed to ground via an external capacitor (0.1 μ F; X5R ceramic or better) and must not be connected to anything else.

Mode 2: 1.8 V \pm 5% External Supply

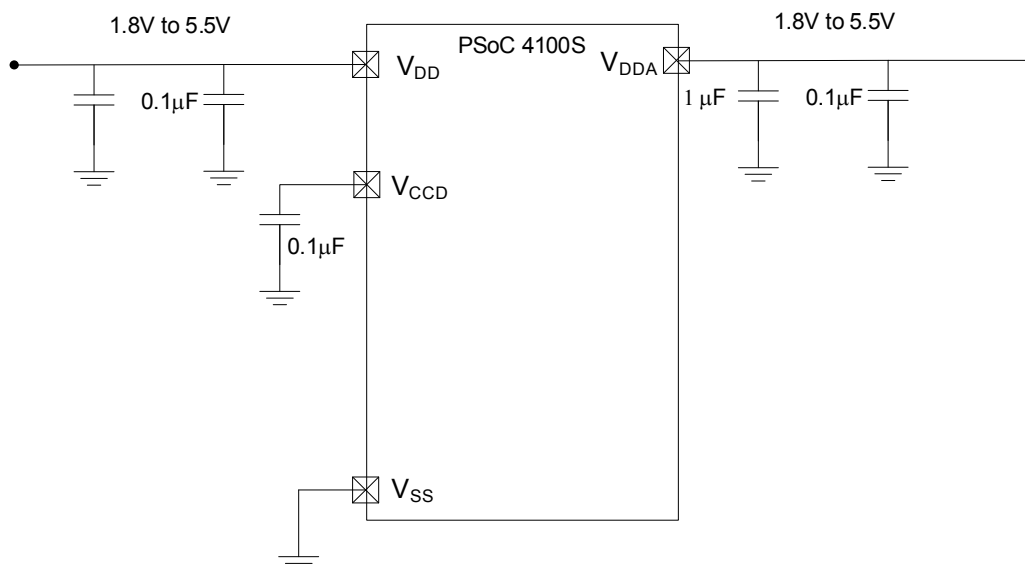
In this mode, the PSoC 4100S is powered by an external power supply that must be within the range of 1.71 to 1.89 V; note that this range needs to include the power supply ripple too. In this mode, the V_{DD} and V_{CCD} pins are shorted together and bypassed. The internal regulator can be disabled in the firmware.

Bypass capacitors must be used from V_{DDD} to ground. The typical practice for systems in this frequency range is to use a capacitor in the 1- μ F range, in parallel with a smaller capacitor (0.1 μ F, for example). Note that these are simply rules of thumb and that, for critical applications, the PCB layout, lead inductance, and the bypass capacitor parasitic should be simulated to design and obtain optimal bypassing.

An example of a bypass scheme is shown in the following diagram.

Figure 5. External Supply Range from 1.8 V to 5.5 V with Internal Regulator Active

Power supply bypass connections example



Electrical Specifications

Absolute Maximum Ratings

Table 2. Absolute Maximum Ratings^[1]

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID1	V _{DDD_ABS}	Digital supply relative to V _{SS}	−0.5	−	6	V	−
SID2	V _{CCD_ABS}	Direct digital core voltage input relative to V _{SS}	−0.5	−	1.95		−
SID3	V _{GPIO_ABS}	GPIO voltage	−0.5	−	V _{DD} +0.5		−
SID4	I _{GPIO_ABS}	Maximum current per GPIO	−25	−	25	mA	−
SID5	I _{GPIO_injection}	GPIO injection current, Max for V _{IH} > V _{DDD} , and Min for V _{IL} < V _{SS}	−0.5	−	0.5		Current injected per pin
BID44	ESD_HBM	Electrostatic discharge human body model	2200	−	−	V	−
BID45	ESD_CDM	Electrostatic discharge charged device model	500	−	−		−
BID46	LU	Pin current for latch-up	−140	−	140	mA	−

Device Level Specifications

All specifications are valid for $-40\text{ }^{\circ}\text{C} \leq T_A \leq 85\text{ }^{\circ}\text{C}$ and $T_J \leq 100\text{ }^{\circ}\text{C}$, except where noted. Specifications are valid for 1.71 V to 5.5 V, except where noted.

Table 3. DC Specifications

Typical values measured at V_{DD} = 3.3 V and 25 °C.

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID53	V _{DD}	Power supply input voltage	1.8	−	5.5	V	Internally regulated supply
SID255	V _{DD}	Power supply input voltage (V _{CCD} = V _{DDD} = V _{DDA})	1.71	−	1.89		Internally unregulated supply
SID54	V _{CCD}	Output voltage (for core logic)	−	1.8	−		−
SID55	C _{EFC}	External regulator voltage bypass	−	0.1	−	μF	X5R ceramic or better
SID56	C _{EXC}	Power supply bypass capacitor	−	1	−		X5R ceramic or better

Active Mode, V_{DD} = 1.8 V to 5.5 V. Typical values measured at V_{DD} = 3.3 V and 25 °C.

SID10	I _{DD5}	Execute from flash; CPU at 6 MHz	−	1.8	2.7	mA	Max is at 85 °C and 5.5 V
SID16	I _{DD8}	Execute from flash; CPU at 24 MHz	−	3.0	4.75		Max is at 85 °C and 5.5 V
SID19	I _{DD11}	Execute from flash; CPU at 48 MHz	−	5.4	6.85		Max is at 85 °C and 5.5 V

Note

- Usage above the absolute maximum conditions listed in Table 2 may cause permanent damage to the device. Exposure to Absolute Maximum conditions for extended periods of time may affect device reliability. The Maximum Storage Temperature is 150 °C in compliance with JEDEC Standard JESD22-A103, High Temperature Storage Life. When used below Absolute Maximum conditions but above normal operating conditions, the device may not operate to specification.

Table 3. DC Specifications (continued)

Typical values measured at $V_{DD} = 3.3\text{ V}$ and $25\text{ }^{\circ}\text{C}$.

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
Sleep Mode, VDDD = 1.8 V to 5.5 V (Regulator on)							
SID22	IDD17	I ² C wakeup WDT, and Comparators on	–	1.7	2.2	mA	6 MHZ. Max is at 85 °C and 5.5 V.
SID25	IDD20	I ² C wakeup, WDT, and Comparators on.	–	2.2	2.5		12 MHZ. Max is at 85 °C and 5.5 V.
Sleep Mode, VDDD = 1.71 V to 1.89 V (Regulator bypassed)							
SID28	IDD23	I ² C wakeup, WDT, and Comparators on	–	0.7	0.9	mA	6 MHZ. Max is at 85 °C and 5.5 V.
SID28A	IDD23A	I ² C wakeup, WDT, and Comparators on	–	1	1.2	mA	12 MHZ. Max is at 85 °C and 5.5 V.
Deep Sleep Mode, VDD = 1.8 V to 3.6 V (Regulator on)							
SID31	IDD26	I ² C wakeup and WDT on	–	2.5	60	μA	Max is at 3.6 V and 85 °C.
Deep Sleep Mode, VDD = 3.6 V to 5.5 V (Regulator on)							
SID34	IDD29	I ² C wakeup and WDT on	–	2.5	60	μA	Max is at 5.5 V and 85 °C.
Deep Sleep Mode, VDD = VCCD = 1.71 V to 1.89 V (Regulator bypassed)							
SID37	IDD32	I ² C wakeup and WDT on	–	2.5	65	μA	Max is at 1.89 V and 85 °C.
XRES Current							
SID307	IDD_XR	Supply current while XRES asserted	–	2	5	mA	–

Table 4. AC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID48	F _{CPU}	CPU frequency	DC	–	48	MHz	$1.71 \leq V_{DD} \leq 5.5$
SID49 ^[3]	T _{SLEEP}	Wakeup from Sleep mode	–	0	–	μs	
SID50 ^[3]	T _{DEEPSLEEP}	Wakeup from Deep Sleep mode	–	35	–		

Note

2. Guaranteed by characterization.

GPIO
Table 5. GPIO DC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID57	$V_{IH}^{[3]}$	Input voltage high threshold	$0.7 \times V_{DD}$	–	–	V	CMOS Input
SID58	V_{IL}	Input voltage low threshold	–	–	$0.3 \times V_{DD}$		CMOS Input
SID241	$V_{IH}^{[3]}$	LVTTL input, $V_{DD} < 2.7$ V	$0.7 \times V_{DD}$	–	–		–
SID242	V_{IL}	LVTTL input, $V_{DD} < 2.7$ V	–	–	$0.3 \times V_{DD}$		–
SID243	$V_{IH}^{[3]}$	LVTTL input, $V_{DD} \geq 2.7$ V	2.0	–	–		–
SID244	V_{IL}	LVTTL input, $V_{DD} \geq 2.7$ V	–	–	0.8		–
SID59	V_{OH}	Output voltage high level	$V_{DD} - 0.6$	–	–		$I_{OH} = 4$ mA at 3 V V_{DD}
SID60	V_{OH}	Output voltage high level	$V_{DD} - 0.5$	–	–		$I_{OH} = 1$ mA at 1.8 V V_{DD}
SID61	V_{OL}	Output voltage low level	–	–	0.6		$I_{OL} = 4$ mA at 1.8 V V_{DD}
SID62	V_{OL}	Output voltage low level	–	–	0.6		$I_{OL} = 10$ mA at 3 V V_{DD}
SID62A	V_{OL}	Output voltage low level	–	–	0.4		$I_{OL} = 3$ mA at 3 V V_{DD}
SID63	R_{PULLUP}	Pull-up resistor	3.5	5.6	8.5	k Ω	–
SID64	$R_{PULLDOWN}$	Pull-down resistor	3.5	5.6	8.5		–
SID65	I_{IL}	Input leakage current (absolute value)	–	–	2	nA	25 °C, $V_{DD} = 3.0$ V
SID66	C_{IN}	Input capacitance	–	–	7	pF	–
SID67 ^[4]	V_{HYSTTL}	Input hysteresis LVTTL	25	40	–	mV	$V_{DD} \geq 2.7$ V
SID68 ^[4]	$V_{HYSCMOS}$	Input hysteresis CMOS	$0.05 \times V_{DD}$	–	–		$V_{DD} < 4.5$ V
SID68A ^[4]	$V_{HYSCMOS5V5}$	Input hysteresis CMOS	200	–	–		$V_{DD} > 4.5$ V
SID69 ^[4]	I_{DIODE}	Current through protection diode to V_{DD}/V_{SS}	–	–	100	μ A	–
SID69A ^[4]	I_{TOT_GPIO}	Maximum total source or sink chip current	–	–	200	mA	–

Table 6. GPIO AC Specifications

(Guaranteed by Characterization)

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID70	T_{RISEF}	Rise time in fast strong mode	2	–	12	ns	3.3 V V_{DD} , Load = 25 pF
SID71	T_{FALLF}	Fall time in fast strong mode	2	–	12		3.3 V V_{DD} , Load = 25 pF
SID72	T_{RISES}	Rise time in slow strong mode	10	–	60	–	3.3 V V_{DD} , Load = 25 pF

Notes

3. V_{IH} must not exceed $V_{DD} + 0.2$ V.
4. Guaranteed by characterization.

Analog Peripherals

Table 9. CTBm Opamp Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
	I _{DD}	Opamp block current, External load					
SID269	I _{DD_HI}	power=hi	–	1100	1850	μA	–
SID270	I _{DD_MED}	power=med	–	550	950		–
SID271	I _{DD_LOW}	power=lo	–	150	350		–
	G _{BW}	Load = 20 pF, 0.1 mA V _{D_{DDA}} = 2.7 V					
SID272	G _{BW_HI}	power=hi	6	–	–	MHz	Input and output are 0.2 V to V _{D_{DDA}} -0.2 V
SID273	G _{BW_MED}	power=med	3	–	–		Input and output are 0.2 V to V _{D_{DDA}} -0.2 V
SID274	G _{BW_LO}	power=lo	–	1	–		Input and output are 0.2 V to V _{D_{DDA}} -0.2 V
	I _{OUT_MAX}	V _{D_{DDA}} = 2.7 V, 500 mV from rail					
SID275	I _{OUT_MAX_HI}	power=hi	10	–	–	mA	Output is 0.5 V V _{D_{DDA}} -0.5 V
SID276	I _{OUT_MAX_MID}	power=mid	10	–	–		Output is 0.5 V V _{D_{DDA}} -0.5 V
SID277	I _{OUT_MAX_LO}	power=lo	–	5	–		Output is 0.5 V V _{D_{DDA}} -0.5 V
	I _{OUT}	V _{D_{DDA}} = 1.71 V, 500 mV from rail					
SID278	I _{OUT_MAX_HI}	power=hi	4	–	–	mA	Output is 0.5 V V _{D_{DDA}} -0.5 V
SID279	I _{OUT_MAX_MID}	power=mid	4	–	–		Output is 0.5 V V _{D_{DDA}} -0.5 V
SID280	I _{OUT_MAX_LO}	power=lo	–	2	–		Output is 0.5 V V _{D_{DDA}} -0.5 V
	I _{DD_Int}	Opamp block current Internal Load					
SID269_I	I _{DD_HI_Int}	power=hi	–	1500	1700	μA	–
SID270_I	I _{DD_MED_Int}	power=med	–	700	900		–
SID271_I	I _{DD_LOW_Int}	power=lo	–	–	–		–
	G _{BW}	V _{D_{DDA}} = 2.7 V	–	–	–		–
SID272_I	G _{BW_HI_Int}	power=hi	8	–	–	MHz	Output is 0.25 V to V _{D_{DDA}} -0.25 V

Table 9. CTBm Opamp Specifications *(continued)*

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID299	T_OP_WAKE	From disable to enable, no external RC dominating	–	–	25	µs	–
SID299A	OL_GAIN	Open Loop Gain	–	90	–	dB	
	COMP_MODE	Comparator mode; 50 mV drive, $T_{rise}=T_{fall}$ (approx.)					
SID300	TPD1	Response time; power=hi	–	150	–	ns	Input is 0.2 V to $V_{DDA}-0.2$ V
SID301	TPD2	Response time; power=med	–	500	–		Input is 0.2 V to $V_{DDA}-0.2$ V
SID302	TPD3	Response time; power=lo	–	2500	–		Input is 0.2 V to $V_{DDA}-0.2$ V
SID303	VHYST_OP	Hysteresis	–	10	–	mV	–
SID304	WUP_CTB	Wake-up time from Enabled to Usable	–	–	25	µs	–
	Deep Sleep Mode	Mode 2 is lowest current range. Mode 1 has higher GBW.					
SID_DS_1	I _{DD_HI_M1}	Mode 1, High current	–	1400	–	µA	25 °C
SID_DS_2	I _{DD_MED_M1}	Mode 1, Medium current	–	700	–		25 °C
SID_DS_3	I _{DD_LOW_M1}	Mode 1, Low current	–	200	–		25 °C
SID_DS_4	I _{DD_HI_M2}	Mode 2, High current	–	120	–		25 °C
SID_DS_5	I _{DD_MED_M2}	Mode 2, Medium current	–	60	–		25 °C
SID_DS_6	I _{DD_LOW_M2}	Mode 2, Low current	–	15	–		25 °C

Table 10. Comparator DC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID84	V _{OFFSET1}	Input offset voltage, Factory trim	–	–	±10	mV	
SID85	V _{OFFSET2}	Input offset voltage, Custom trim	–	–	±4		
SID86	V _{HYST}	Hysteresis when enabled	–	10	35		
SID87	V _{ICM1}	Input common mode voltage in normal mode	0	–	V _{DDD} -0.1	V	Modes 1 and 2
SID247	V _{ICM2}	Input common mode voltage in low power mode	0	–	V _{DDD}		
SID247A	V _{ICM3}	Input common mode voltage in ultra low power mode	0	–	V _{DDD} -1.15		V _{DDD} ≥ 2.2 V at –40 °C
SID88	C _{MRR}	Common mode rejection ratio	50	–	–	dB	V _{DDD} ≥ 2.7V
SID88A	C _{MRR}	Common mode rejection ratio	42	–	–		V _{DDD} ≤ 2.7V
SID89	I _{CMP1}	Block current, normal mode	–	–	400	μA	
SID248	I _{CMP2}	Block current, low power mode	–	–	100		
SID259	I _{CMP3}	Block current in ultra low-power mode	–	–	6		V _{DDD} ≥ 2.2 V at –40 °C
SID90	Z _{CMP}	DC Input impedance of comparator	35	–	–	MΩ	

Table 11. Comparator AC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID91	TRESP1	Response time, normal mode, 50 mV overdrive	–	38	110	ns	
SID258	TRESP2	Response time, low power mode, 50 mV overdrive	–	70	200		
SID92	TRESP3	Response time, ultra-low power mode, 200 mV overdrive	–	2.3	15	μs	V _{DDD} ≥ 2.2 V at –40 °C

Table 12. Temperature Sensor Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SID93	TSENSACC	Temperature sensor accuracy	–5	±1	5	°C	–40 to +85 °C

Table 13. SAR Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SAR ADC DC Specifications							
SID94	A_RES	Resolution	–	–	12	bits	
SID95	A_CHNLS_S	Number of channels - single ended	–	–	16		
SID96	A-CHNKS_D	Number of channels - differential	–	–	4		Diff inputs use neighboring I/O
SID97	A-MONO	Monotonicity	–	–	–		Yes.
SID98	A_GAINERR	Gain error	–	–	±0.1	%	With external reference.

Table 13. SAR Specifications (continued)

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID99	A_OFFSET	Input offset voltage	–	–	2	mV	Measured with 1-V reference
SID100	A_ISAR	Current consumption	–	–	1	mA	
SID101	A_VINS	Input voltage range - single ended	V_{SS}	–	V_{DDA}	V	
SID102	A_VIND	Input voltage range - differential[V_{SS}	–	V_{DDA}	V	
SID103	A_INRES	Input resistance	–	–	2.2	K Ω	
SID104	A_INCAP	Input capacitance	–	–	10	pF	
SID260	VREFSAR	Trimmed internal reference to SAR	–	–	TBD	V	
SAR ADC AC Specifications							
SID106	A_PSRR	Power supply rejection ratio	70	–	–	dB	
SID107	A_CMRR	Common mode rejection ratio	66	–	–	dB	Measured at 1 V
SID108	A_SAMP	Sample rate	–	–	1	Msps	
SID109	A_SNR	Signal-to-noise and distortion ratio (SINAD)	65	–	–	dB	$F_{IN} = 10$ kHz
SID110	A_BW	Input bandwidth without aliasing	–	–	$A_{\text{samp}}/2$	kHz	
SID111	A_INL	Integral non linearity. $V_{DD} = 1.71$ to 5.5, 1 Msps	–1.7	–	2	LSB	$V_{REF} = 1$ to V_{DD}
SID111A	A_INL	Integral non linearity. $V_{DD} = 1.71$ to 3.6, 1 Msps	–1.5	–	1.7	LSB	$V_{REF} = 1.71$ to V_{DD}
SID111B	A_INL	Integral non linearity. $V_{DD} = 1.71$ to 5.5, 500 ksps	–1.5	–	1.7	LSB	$V_{REF} = 1$ to V_{DD}
SID112	A_DNL	Differential non linearity. $V_{DD} = 1.71$ to 5.5, 1 Msps	–1	–	2.2	LSB	$V_{REF} = 1$ to V_{DD}
SID112A	A_DNL	Differential non linearity. $V_{DD} = 1.71$ to 3.6, 1 Msps	–1	–	2	LSB	$V_{REF} = 1.71$ to V_{DD}
SID112B	A_DNL	Differential non linearity. $V_{DD} = 1.71$ to 5.5, 500 ksps	–1	–	2.2	LSB	$V_{REF} = 1$ to V_{DD}
SID113	A_THD	Total harmonic distortion	–	–	–65	dB	$F_{in} = 10$ kHz
SID261	FSARINTRE F	SAR operating speed without external ref. bypass	–	–	100	ksps	12-bit resolution

CSD

Table 14. CSD and IDAC Specifications

SPEC ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SYS.PER#3	VDD_RIPPLE	Max allowed ripple on power supply, DC to 10 MHz	–	–	±50	mV	$V_{DD} > 2\text{ V}$ (with ripple), 25°C T_A , Sensitivity = 0.1 pF
SYS.PER#16	VDD_RIPPLE_1.8	Max allowed ripple on power supply, DC to 10 MHz	–	–	±25	mV	$V_{DD} > 1.75\text{V}$ (with ripple), 25°C T_A , Parasitic Capacitance (C_P) < 20 pF, Sensitivity ≥ 0.4 pF
SID.CSD.BLK	ICSD	Maximum block current	–	–	4000	μA	Maximum block current for both IDACs in dynamic (switching) mode including comparators, buffer, and reference generator.
SID.CSD#15	V _{REF}	Voltage reference for CSD and Comparator	0.6	1.2	$V_{DDA} - 0.6$	V	$V_{DDA} - 0.06$ or 4.4, whichever is lower
SID.CSD#15A	VREF_EXT	External Voltage reference for CSD and Comparator	0.6		$V_{DDA} - 0.6$	V	$V_{DDA} - 0.06$ or 4.4, whichever is lower
SID.CSD#16	IDAC1IDD	IDAC1 (7-bits) block current	–	–	1750	μA	
SID.CSD#17	IDAC2IDD	IDAC2 (7-bits) block current	–	–	1750	μA	
SID308	VCSD	Voltage range of operation	1.71	–	5.5	V	1.8 V ±5% or 1.8 V to 5.5 V
SID308A	VCOMPIDAC	Voltage compliance range of IDAC	0.6	–	$V_{DDA} - 0.6$	V	$V_{DDA} - 0.06$ or 4.4, whichever is lower
SID309	IDAC1DNL	DNL	–1	–	1	LSB	
SID310	IDAC1INL	INL	–2	–	2	LSB	INL is ±5.5 LSB for $V_{DDA} < 2\text{ V}$
SID311	IDAC2DNL	DNL	–1	–	1	LSB	
SID312	IDAC2INL	INL	–2	–	2	LSB	INL is ±5.5 LSB for $V_{DDA} < 2\text{ V}$
SID313	SNR	Ratio of counts of finger to noise. Guaranteed by characterization	5	–	–	Ratio	Capacitance range of 5 to 35 pF, 0.1-pF sensitivity. All use cases. $V_{DDA} > 2\text{ V}$.
SID314	IDAC1CRT1	Output current of IDAC1 (7 bits) in low range	4.2	–	5.4	μA	LSB = 37.5-nA typ.
SID314A	IDAC1CRT2	Output current of IDAC1 (7 bits) in medium range	34	–	41	μA	LSB = 300-nA typ.
SID314B	IDAC1CRT3	Output current of IDAC1 (7 bits) in high range	275	–	330	μA	LSB = 2.4-μA typ.
SID314C	IDAC1CRT12	Output current of IDAC1 (7 bits) in low range, 2X mode	8	–	10.5	μA	LSB = 75-nA typ.
SID314D	IDAC1CRT22	Output current of IDAC1 (7 bits) in medium range, 2X mode	69	–	82	μA	LSB = 600-nA typ.
SID314E	IDAC1CRT32	Output current of IDAC1 (7 bits) in high range, 2X mode	540	–	660	μA	LSB = 4.8-μA typ.
SID315	IDAC2CRT1	Output current of IDAC2 (7 bits) in low range	4.2	–	5.4	μA	LSB = 37.5-nA typ.
SID315A	IDAC2CRT2	Output current of IDAC2 (7 bits) in medium range	34	–	41	μA	LSB = 300-nA typ.
SID315B	IDAC2CRT3	Output current of IDAC2 (7 bits) in high range	275	–	330	μA	LSB = 2.4-μA typ.
SID315C	IDAC2CRT12	Output current of IDAC2 (7 bits) in low range, 2X mode	8	–	10.5	μA	LSB = 75-nA typ.
SID315D	IDAC2CRT22	Output current of IDAC2 (7 bits) in medium range, 2X mode	69	–	82	μA	LSB = 600-nA typ.
SID315E	IDAC2CRT32	Output current of IDAC2 (7 bits) in high range, 2X mode	540	–	660	μA	LSB = 4.8-μA typ.
SID315F	IDAC3CRT13	Output current of IDAC in 8-bit mode in low range	8	–	10.5	μA	LSB = 37.5-nA typ.

Table 21. UART DC Specifications^[9]

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID160	I _{UART1}	Block current consumption at 100 Kbps	–	–	55	μA	–
SID161	I _{UART2}	Block current consumption at 1000 Kbps	–	–	312	μA	–

Table 22. UART AC Specifications^[9]

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID162	F _{UART}	Bit rate	–	–	1	Mbps	–

Table 23. LCD Direct Drive DC Specifications^[9]

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID154	I _{LCDLOW}	Operating current in low power mode	–	5	–	μA	16 × 4 small segment disp. at 50 Hz
SID155	C _{LDCAP}	LCD capacitance per segment/common driver	–	500	5000	pF	–
SID156	LCD _{OFFSET}	Long-term segment offset	–	20	–	mV	–
SID157	I _{LCDOP1}	LCD system operating current V _{bias} = 5 V	–	2	–	mA	32 × 4 segments. 50 Hz. 25 °C
SID158	I _{LCDOP2}	LCD system operating current V _{bias} = 3.3 V	–	2	–		32 × 4 segments. 50 Hz. 25 °C

Table 24. LCD Direct Drive AC Specifications^[9]

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID159	F _{LCD}	LCD frame rate	10	50	150	Hz	–

Note

9. Guaranteed by characterization.

Memory

Table 25. Flash DC Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID173	V _{PE}	Erase and program voltage	1.71	–	5.5	V	–

Table 26. Flash AC Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID174	T _{ROWWRITE} ^[10]	Row (block) write time (erase and program)	–	–	20	ms	Row (block) = 128 bytes
SID175	T _{ROWERASE} ^[10]	Row erase time	–	–	16		–
SID176	T _{ROWPROGRAM} ^[10]	Row program time after erase	–	–	4		–
SID178	T _{BULKERASE} ^[10]	Bulk erase time (64 KB)	–	–	35		–
SID180 ^[11]	T _{DEVPROG} ^[10]	Total device program time	–	–	7	Seconds	–
SID181 ^[11]	F _{END}	Flash endurance	100 K	–	–	Cycles	–
SID182 ^[11]	F _{RET}	Flash retention. T _A ≤ 55 °C, 100 K P/E cycles	20	–	–	Years	–
SID182A ^[11]	–	Flash retention. T _A ≤ 85 °C, 10 K P/E cycles	10	–	–		–
SID256	TWS48	Number of Wait states at 48 MHz	2	–	–		CPU execution from Flash
SID257	TWS24	Number of Wait states at 24 MHz	1	–	–		CPU execution from Flash

System Resources

Power-on Reset (POR)

Table 27. Power On Reset (PRES)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID.CLK#6	SR_POWER_UP	Power supply slew rate	1	–	67	V/ms	At power-up
SID185 ^[11]	V _{RISEIPOR}	Rising trip voltage	0.80	–	1.5	V	–
SID186 ^[11]	V _{FALLIPOR}	Falling trip voltage	0.70	–	1.4		–

Table 28. Brown-out Detect (BOD) for V_{CCD}

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID190 ^[11]	V _{FALLPPOR}	BOD trip voltage in active and sleep modes	1.48	–	1.62	V	–
SID192 ^[11]	V _{FALLDPSLP}	BOD trip voltage in Deep Sleep	1.11	–	1.5		–

Notes

10. It can take as much as 20 milliseconds to write to Flash. During this time the device should not be Reset, or Flash operations will be interrupted and cannot be relied on to have completed. Reset sources include the XRES pin, software resets, CPU lockup states and privilege violations, improper power supply levels, and watchdogs. Make certain that these are not inadvertently activated.

11. Guaranteed by characterization.

Table 34. Watch Crystal Oscillator (WCO) Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SID398	FWCO	Crystal Frequency	–	32.768	–	kHz	
SID399	FTOL	Frequency tolerance	–	50	250	ppm	With 20-ppm crystal
SID400	ESR	Equivalent series resistance	–	50	–	kΩ	
SID401	PD	Drive Level	–	–	1	μW	
SID402	TSTART	Startup time	–	–	500	ms	
SID403	CL	Crystal Load Capacitance	6	–	12.5	pF	
SID404	C0	Crystal Shunt Capacitance	–	1.35	–	pF	
SID405	IWCO1	Operating Current (high power mode)	–	–	8	uA	
SID406	IWCO2	Operating Current (low power mode)	–	–	1	uA	

Table 35. External Clock Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID305 ^[13]	ExtClkFreq	External clock input frequency	0	–	48	MHz	–
SID306 ^[13]	ExtClkDuty	Duty cycle; measured at V _{DD/2}	45	–	55	%	–

Table 36. Block Specs

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID262 ^[13]	T _{CLKSWITCH}	System clock source switching time	3	–	4	Periods	–

Table 37. Smart I/O Pass-through Time (Delay in Bypass Mode)

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SID252	PRG_BYPASS	Max delay added by Smart I/O in bypass mode	–	–	1.6	ns	

Note

13. Guaranteed by characterization.

Ordering Information

The marketing part numbers for the PSoC 4100S family are listed in the following table.

Category	MPN	Features														Package				
		Max CPU Speed (MHz)	Flash (KB)	SRAM (KB)	Opamp (CTBm)	CSD	10-bit CSD ADC	12-bit SAR ADC	ADC Sample Rate	LP Comparators	TCPWM Blocks	SCB Blocks	Smart I/Os	GPIO	35-WLCSP (0.35mm pitch)	32-QFN	40-QFN	48-TQFP	44-TQFP	
4124	CY8C4124FNI-S403	24	16	4	2	0	1	0		2	5	2	8	31	X					
	CY8C4124FNI-S413	24	16	4	2	1	1	0		2	5	2	16	31	X					
	CY8C4124LQI-S412	24	16	4	2	1	1	0		2	5	2	16	27		X				
	CY8C4124LQI-S413	24	16	4	2	1	1	0		2	5	2	16	34			X			
	CY8C4124AZI-S413	24	16	4	2	1	1	0		2	5	2	16	36				X		
	CY8C4124FNI-S433	24	16	4	2	1	1	1	806 ksp/s	2	5	2	16	31	X					
	CY8C4124LQI-S432	24	16	4	2	1	1	1	806 ksp/s	2	5	2	16	27		X				
	CY8C4124LQI-S433	24	16	4	2	1	1	1	806 ksp/s	2	5	2	16	34			X			
4125	CY8C4124AZI-S433	24	16	4	2	1	1	1	806 ksp/s	2	5	2	16	36				X		
	CY8C4125FNI-S423	24	32	4	2	0	1	1	806 ksp/s	2	5	2	16	31	X					
	CY8C4125LQI-S422	24	32	4	2	0	1	1	806 ksp/s	2	5	2	16	27		X				
	CY8C4125LQI-S423	24	32	4	2	0	1	1	806 ksp/s	2	5	2	16	34			X			
	CY8C4125AZI-S423	24	32	4	2	0	1	1	806 ksp/s	2	5	2	16	36				X		
	CY8C4125AXI-S423	24	32	4	2	0	1	1	806 ksp/s	2	5	2	16	36					X	
	CY8C4125FNI-S413	24	32	4	2	1	1	0		2	5	2	16	31	X					
	CY8C4125LQI-S412	24	32	4	2	1	1	0		2	5	2	16	27		X				
	CY8C4125LQI-S413	24	32	4	2	1	1	0		2	5	2	16	34			X			
	CY8C4125AZI-S413	24	32	4	2	1	1	0		2	5	2	16	36				X		
	CY8C4125FNI-S433	24	32	4	2	1	1	1	806 ksp/s	2	5	2	16	31	X					
	CY8C4125LQI-S432	24	32	4	2	1	1	1	806 ksp/s	2	5	2	16	27		X				
	CY8C4125LQI-S433	24	32	4	2	1	1	1	806 ksp/s	2	5	2	16	34			X			
	CY8C4125AZI-S433	24	32	4	2	1	1	1	806 ksp/s	2	5	2	16	36				X		
CY8C4125AXI-S433	24	32	4	2	1	1	1	806 ksp/s	2	5	2	16	36					X		
4126	CY8C4126AZI-S423	24	64	8	2	0	1	1	806 ksp/s	2	5	3	16	36				X		
	CY8C4126AXI-S423	24	64	8	2	0	1	1	806 ksp/s	2	5	3	16	36					X	
	CY8C4126AZI-S433	24	64	8	2	1	1	1	806 ksp/s	2	5	3	16	36				X		
	CY8C4126AXI-S433	24	64	8	2	1	1	1	806 ksp/s	2	5	3	16	36					X	
4145	CY8C4145AZI-S423	48	32	4	2	0	1	1	1 Msps	2	5	2	16	36				X		
	CY8C4145AXI-S423	48	32	4	2	0	1	1	1 Msps	2	5	2	16	36					X	
	CY8C4145AXI-S433	48	32	4	2	1	1	1	1 Msps	2	5	2	16	36					X	
4146	CY8C4146FNI-S423	48	64	8	2	0	1	1	1 Msps	2	5	3	16	31	X					
	CY8C4146LQI-S422	48	64	8	2	0	1	1	1 Msps	2	5	3	16	27		X				
	CY8C4146LQI-S423	48	64	8	2	0	1	1	1 Msps	2	5	3	16	34			X			
	CY8C4146AZI-S423	48	64	8	2	0	1	1	1 Msps	2	5	3	16	36				X		
	CY8C4146AXI-S423	48	64	8	2	0	1	1	1 Msps	2	5	3	16	36					X	
	CY8C4146FNI-S433	48	64	8	2	1	1	1	1 Msps	2	5	3	16	31	X					
	CY8C4146LQI-S432	48	64	8	2	1	1	1	1 Msps	2	5	3	16	27		X				
	CY8C4146LQI-S433	48	64	8	2	1	1	1	1 Msps	2	5	3	16	34			X			
	CY8C4146AZI-S433	48	64	8	2	1	1	1	1 Msps	2	5	3	16	36				X		
CY8C4146AXI-S433	48	64	8	2	1	1	1	1 Msps	2	5	3	16	36					X		

Packaging

The PSoC 4100S will be offered in 48-pin TQFP, 44-pin TQFP, 40-pin QFN, 32-pin QFN, and 35-ball WLCSP packages. Package dimensions and Cypress drawing numbers are in the following table.

Table 38. Package List

Spec ID#	Package	Description	Package Dwg
BID20	48-pin TQFP	7 × 7 × 1.4-mm height with 0.5-mm pitch	51-85135
BID20A	44-pin TQFP	10 × 10 × 1.6-mm height with 0.8-mm pitch	51-85064
BID27	40-pin QFN	6 × 6 × 0.6-mm height with 0.5-mm pitch	001-80659
BID34A	32-pin QFN	5 × 5 × 0.6-mm height with 0.5-mm pitch	001-42168
BID34D	35-ball WLCSP	2.6 × 2.1 × 0.48-mm height with 0.35-mm pitch	002-09958

Table 39. Package Thermal Characteristics

Parameter	Description	Package	Min	Typ	Max	Units
T _A	Operating Ambient temperature		−40	25	85	°C
T _J	Operating junction temperature		−40	—	100	°C
T _{JA}	Package θ _{JA}	48-pin TQFP	—	74.8	—	°C/Watt
T _{JC}	Package θ _{JC}	48-pin TQFP	—	35.7	—	°C/Watt
T _{JA}	Package θ _{JA}	44-pin TQFP	—	57.2	—	°C/Watt
T _{JC}	Package θ _{JC}	44-pin TQFP	—	17.5	—	°C/Watt
T _{JA}	Package θ _{JA}	40-pin QFN	—	17.8	—	°C/Watt
T _{JC}	Package θ _{JC}	40-pin QFN	—	2.8	—	°C/Watt
T _{JA}	Package θ _{JA}	32-pin QFN	—	19.9	—	°C/Watt
T _{JC}	Package θ _{JC}	32-pin QFN	—	4.3	—	°C/Watt
T _{JA}	Package θ _{JA}	35-ball WLCSP	—	43	—	°C/Watt
T _{JC}	Package θ _{JC}	35-ball WLCSP	—	0.3	—	°C/Watt

Table 40. Solder Reflow Peak Temperature

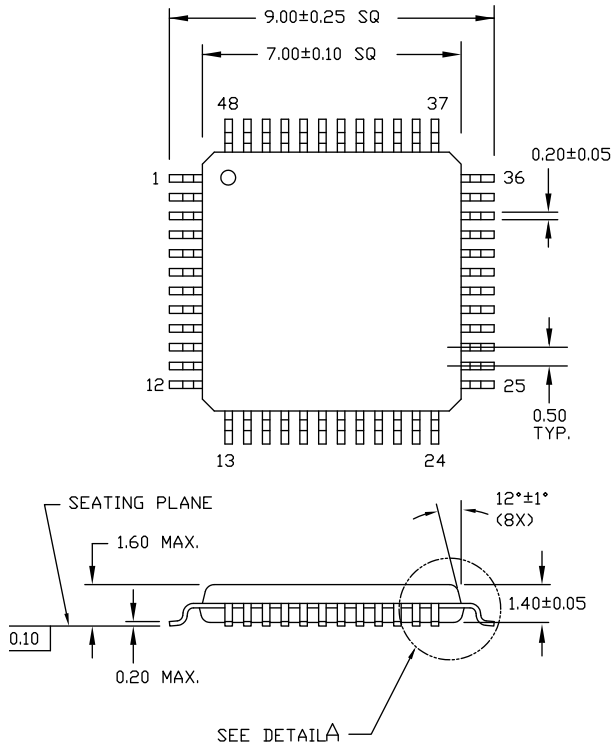
Package	Maximum Peak Temperature	Maximum Time at Peak Temperature
All	260 °C	30 seconds

Table 41. Package Moisture Sensitivity Level (MSL), IPC/JEDEC J-STD-020

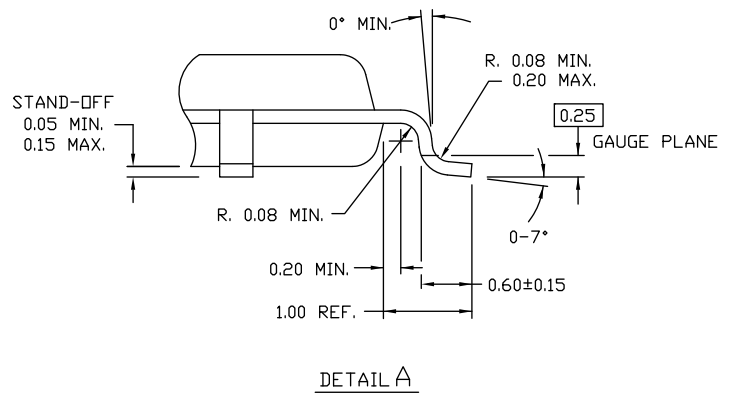
Package	MSL
All except WLCSP	MSL 3
35-ball WLCSP	MSL 1

Package Diagrams

Figure 6. 48-pin TQFP Package Outline

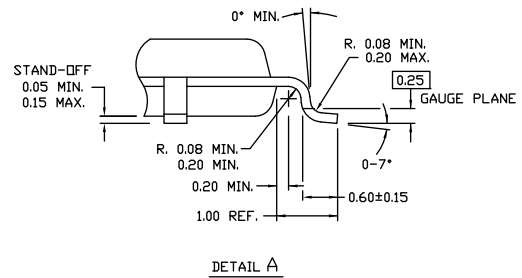
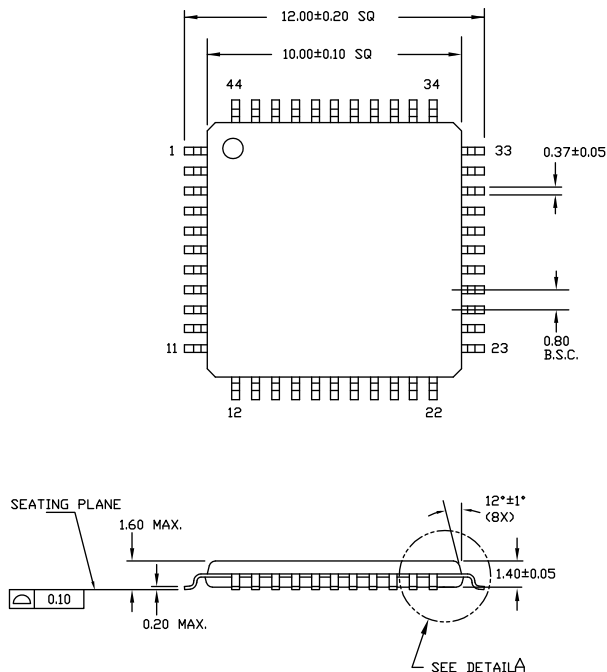


DIMENSIONS ARE IN MILLIMETERS



51-85135 *C

Figure 7. 44-pin TQFP Package Outline

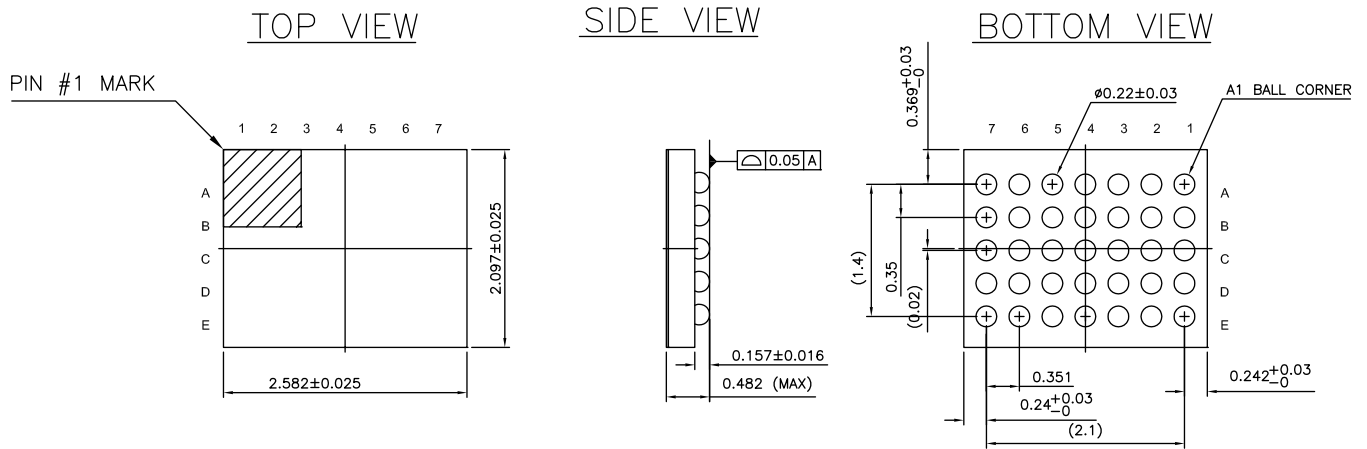


NOTE:

1. JEDEC STD REF MS-026
2. BODY LENGTH DIMENSION DOES NOT INCLUDE MOLD PROTRUSION/END FLASH
MOLD PROTRUSION/END FLASH SHALL NOT EXCEED 0.0098 in (0.25 mm) PER SIDE
BODY LENGTH DIMENSIONS ARE MAX PLASTIC BODY SIZE INCLUDING MOLD MISMATCH
3. DIMENSIONS IN MILLIMETERS

51-85064 *G

Figure 10. 35-Ball WLCSP Package Outline



ALL DIMENSIONS ARE IN MM
JEDEC Publication 95; Design Guide 4.18

002-09958 *C

Table 42. Acronyms Used in this Document *(continued)*

Acronym	Description
PC	program counter
PCB	printed circuit board
PGA	programmable gain amplifier
PHUB	peripheral hub
PHY	physical layer
PICU	port interrupt control unit
PLA	programmable logic array
PLD	programmable logic device, see also PAL
PLL	phase-locked loop
PMDD	package material declaration data sheet
POR	power-on reset
PRES	precise power-on reset
PRS	pseudo random sequence
PS	port read data register
PSoC®	Programmable System-on-Chip™
PSRR	power supply rejection ratio
PWM	pulse-width modulator
RAM	random-access memory
RISC	reduced-instruction-set computing
RMS	root-mean-square
RTC	real-time clock
RTL	register transfer language
RTR	remote transmission request
RX	receive
SAR	successive approximation register
SC/CT	switched capacitor/continuous time
SCL	I ² C serial clock
SDA	I ² C serial data
S/H	sample and hold
SINAD	signal to noise and distortion ratio
SIO	special input/output, GPIO with advanced features. See GPIO.
SOC	start of conversion
SOF	start of frame
SPI	Serial Peripheral Interface, a communications protocol
SR	slew rate
SRAM	static random access memory
SRES	software reset
SWD	serial wire debug, a test protocol

Table 42. Acronyms Used in this Document *(continued)*

Acronym	Description
SWV	single-wire viewer
TD	transaction descriptor, see also DMA
THD	total harmonic distortion
TIA	transimpedance amplifier
TRM	technical reference manual
TTL	transistor-transistor logic
TX	transmit
UART	Universal Asynchronous Transmitter Receiver, a communications protocol
UDB	universal digital block
USB	Universal Serial Bus
USBIO	USB input/output, PSoC pins used to connect to a USB port
VDAC	voltage DAC, see also DAC, IDAC
WDT	watchdog timer
WOL	write once latch, see also NVL
WRES	watchdog timer reset
XRES	external reset I/O pin
XTAL	crystal

Revision History

Description Title: PSoC® 4: PSoC 4100S Family Datasheet Programmable System-on-Chip (PSoC) Document Number: 002-00122				
Revision	ECN	Orig. of Change	Submission Date	Description of Change
**	4883809	WKA	08/28/2015	New datasheet
*A	4992376	WKA	10/30/2015	Updated Pinouts . Added $V_{DDD} \geq 2.2V$ at $-40^{\circ}C$ under Conditions for specs SID247A, SID90, SID92. Updated Table 15 . Updated Ordering Information .
*B	5037826	SLAN	12/08/2015	Changed datasheet status to Preliminary
*C	5060691	WKA	12/22/2015	Updated SCBs from 2 to 3. Updated SRAM size to 8 KB. Changed WLCSP package to 35-ball WLCSP. Updated Pin List and Alternate Pin Functions. Updated Ordering Information .
*D	5139206	WKA	02/16/2016	Added Errata. Added 35 WLCSP package details. Updated θ_{JA} and J_C values for all packages. Updated copyright information at the end of the document.
*E	5173961	WKA	03/15/2016	Updated values for SID79, BID194, SID175, and SID176. Updated CSD and IDAC Specifications . Updated 10-bit CapSense ADC Specifications .
*F	5330930	WKA	07/27/2016	Updated CSD and IDAC Specifications . Updated 10-bit CapSense ADC Specifications . Removed errata.
*G	5473409	WKA	10/13/2016	Added 44 TQFP pin and package details.
*H	5561833	WKA	01/09/2017	Updated Figure 3 . Changed PRGIO references to Smart I/O. Updated DC Specifications . Updated Ordering Information .

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